Technical Query

Primary Contact Information

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Secondary Contact Information

To:
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Phone:

Date: 3/9/2017

Viasystems Contacts	*Primary*	*Secondary*	*Field Application Engineer*
Customer Service:	Teri Mirza	Dennis Hanley	Todd Henninger
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Technical Support:	Kirti Patel		
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PLEASE, COPY ALL ABOVE ON ALL CORRESPONDENCES

Customer Name:	**DEBRON INDUSTRIAL ELECTRONICS**
Customer P/N:	**40-00624-00LF**
Rev #:	**-**
Site Tooling P/N:	**170892**
Viasystems P/N:	
Order Type:	**Manufacturing Build**

Site : TO

Data

Issue #	**Status**	**Issue**	**Proposed Resolution**	**Customer Response**	**Links**
1	On Hold-Not Started	Please see an attached Gerber Data For Your Approval.			
2	On Hold-Not Started	We will Provide ENIG (Immersion Gold) Per IPC-4552, Which is 118 Micro-Inches of Minimum Nickel Followed by 2 Micro-Inches of Minimum Gold. Please Confirm.			
3	On Hold-Not Started	We will Build this Part Per IPC 6012 Class 2 Per Quotation. Please Confirm.			

4	On Hold- Not Started	The milling on bottom side is cutting 2 holes at R958 and mounting hole on rail as shown in the image. Please advise if this is acceptable or not.			Image
5	On Hold- Not Started	One 2.7 mm pth hole is tenting by solder mask on top side as shown in image. We have added a mask clearance the same as on bottom side to open it up. Please advise if this is acceptable.			Image
6	On Hold- Not Started	As per drawing note there is no solder mask "tenting" of any of the vias or component pin holes. However in the data on top side the vias under BGA Meg_S1, Meg_s2, U1, U25, Trn_MP1, Rec_MP2, and all TRANS# are tented by solder mask. On bottom side the vias under U504, U507 and DCDC9 are tented by mask too. For these via holes we have added a mask relief of drill +6 mil to the tented side. As per via plug layers, the U504, U507 and DCDC9 are to be plugged, please advise if via plug is required for the BGA devices or not.			
7	On Hold- Not Started	On outer layers under the back drilled locations we have changed the copper pads to drill + 4 mil so that the pads will be totally removed at final by back drill holes. Please advise whether this is acceptable.			

8	On Hold-Not Started	We are unable to plug the via holes from both sides. As per our process for via holes that are tented by solder mask on one side and opened on the other side, we will do the button print plugging from the tented side with a mask relief of drill + 6 mil. Please advise if this is acceptable or not.			